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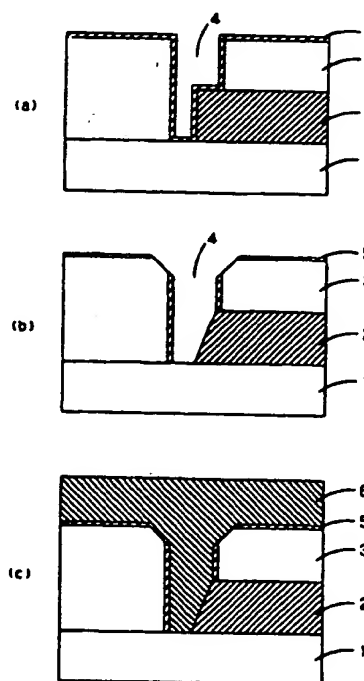
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(54) Semiconductor device having a multi-layered wire structure

(57) After forming a first wire (2) on a first interlayer insulation film (1), a second interlayer insulation film (3) is formed and planarized, to thereby form a via hole (4). At this stage, the via hole is formed off the first wire. Next, after making an exposed edge and an exposed side wall of the first wire slanted surfaces, a second wire (5) is formed with or without a conductive film buried within the via hole. Since the side wall of the first wire is a slanted surface in this manner, it is possible to completely bury a wire material of the second wire or the conductive film within the via hole, and therefore, it is possible to ensure electric conduction all over the slanted surfaces of the first wire. As a result, even if the via hole which connects the first wire in a lower layer and the second wire in an upper layer is formed off the first wire, an increase in a wire resistance in the via hole is prevented.

Fig. 1



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EUROPEAN SEARCH REPORT

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The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 19 Apr 11 1999	Examiner Odgers, M
CATEGORY OF CITED DOCUMENTS X: particularly relevant if taken alone Y: particularly relevant if combined with another document of the same category A: technological background O: non-written disclosure P: intermediate document T: theory or principle underlying the invention E: earlier patent document, but published on, or after the filing date D: document cited in the application L: document cited for other reasons & : member of the same patent family, corresponding document			

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**ANNEX TO THE EUROPEAN SEARCH REPORT
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